

and ejector pins 14 and 15 are used to eject and thus release resin molded body 13 from upper and lower cavities 3 and 4.

In the Claims:

- 1 1. (amended) A die used for sealing and molding an electronic
2 component with a resin material, having a coating layer
3 consisting of nickel-tungsten alloy on at least a surface
4 thereof contacting the resin material in a melted state
5 when the resin material is molded, wherein said coating
6 layer is a plating layer formed of said nickel-tungsten
7 alloy, which contains at least 20% by weight and at most
8 60% by weight of tungsten.
- [Handwritten signature/initials: J. S. B. T.]*

Please cancel claims 2 and 3.

Claim 4 is maintained unchanged.

- 1 5. (amended) The die of claim 1, comprising:
2 a fixed die;
3 a movable die arranged opposite to the fixed die;
4 upper and lower cavities provided in said fixed die
5 and said movable die in respective die planes thereof to
6 face each other along a parting-line plane of said fixed
7 die and said movable die, for molding the resin material;
- [Handwritten signature/initials: J. S. B. T.]*

8 a concavity receiving and setting a support having the
9 electronic component mounted thereto;

10 a pot arranged at one of said fixed die and said
11 movable die for supplying the resin material;

12 a plunger fit internal to said pot for applying
13 pressure to the resin material; and

14 a resin channel to allow said pot and said upper
15 cavity to communicate with each other for transporting the
16 resin material in the melted state,

17 wherein said coating layer is provided on an internal
18 surface of said upper and lower cavities, an internal
19 surface of said resin channel, an internal surface of said
20 concavity, an internal surface of said pot, said
21 parting-line plane of each of said fixed die and said
22 movable die, and an external surface of said plunger.

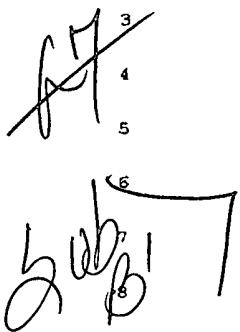
Claim 6 is maintained unchanged.

1 7. (amended) The die of claim 5, wherein said resin channel
2 includes a cull and a runner and gate arranged opposite to
3 said pot for dispensing the resin material in the melted
4 state, said cull and said runner and gate having an
5 internal surface provided with said coating layer.

Claim 8 is maintained unchanged.

Please enter new claims 9 to 11 as follows.

1 9. (new) The die of claim 1, wherein said nickel-tungsten
2 alloy contains at most 40% by weight of said tungsten.

1 10. (new) A molding die for molding an electronic component
2 with a resin, comprising at least one die member body and
3 a coating layer provided on said at least one die member
4 body to form a surface of said molding die that is directly
5 exposed to and directly contacts the resin for reducing
6 adhesion of the resin on said surface, wherein said coating
7 layer is an electroplated layer consisting of a binary
8 alloy of nickel and from 20 to 60% by weight of tungsten.


1 11. (new) The molding die of claim 10, wherein said alloy
2 contains no more than 40% by weight of said tungsten.

REMARKS:

- 1) Referring to item 10) of the Office Action Summary, the Examiner is respectfully requested to indicate whether the original drawings have been accepted, in the next official communication.
- 2) Referring to item 13) of the Office Action Summary, the Examiner is respectfully requested to x-mark sub-box 13)a)1, to complete the acknowledgment that the certified copy of the Priority Document has been received. Namely, it appears that sub-box 13)a)1 was inadvertently left blank.